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FEATURES

Operating RF and LO frequency: 400 MHz to 6 GHz

Input IP3

30 dBm at 900 MHz

28 dBm at 1900 MHz

Input IP2: >65 dBm at 900 MHz

Input P1dB (IP1dB): 11.6 dBm at 900 MHz

Noise figure (NF)

10.9 dB at 900 MHz

11.7 dB at 1900 MHz

Voltage conversion gain: ~7 dB

Quadrature demodulation accuracy at 900 MHz

Phase accuracy: ~0.2°

Amplitude balance: ~0.07 dB

Demodulation bandwidth: ~390 MHz

Baseband I/Q drive: 2 V p-p into 200 Ω

Single 5 V supply

APPLICATIONS

Cellular W-CDMA/GSM/LTE

Microwave point-to-(multi)point radios

Broadband wireless and WiMAX

GENERAL DESCRIPTION

The **ADL5380** is a broadband quadrature I-Q demodulator that covers an RF/IF input frequency range from 400 MHz to 6 GHz. With a NF = 10.9 dB, IP1dB = 11.6 dBm, and IIP3 = 29.7 dBm at 900 MHz, the **ADL5380** demodulator offers outstanding dynamic range suitable for the demanding infrastructure direct-conversion requirements. The differential RF inputs provide a well-behaved broadband input impedance of 50 Ω and are best driven from a 1:1 balun for optimum performance.

Excellent demodulation accuracy is achieved with amplitude and phase balances of ~0.07 dB and ~0.2°, respectively. The demodulated in-phase (I) and quadrature (Q) differential outputs are fully buffered and provide a voltage conversion gain of ~7 dB. The buffered baseband outputs are capable of driving a 2 V p-p differential signal into 200 Ω.

FUNCTIONAL BLOCK DIAGRAM

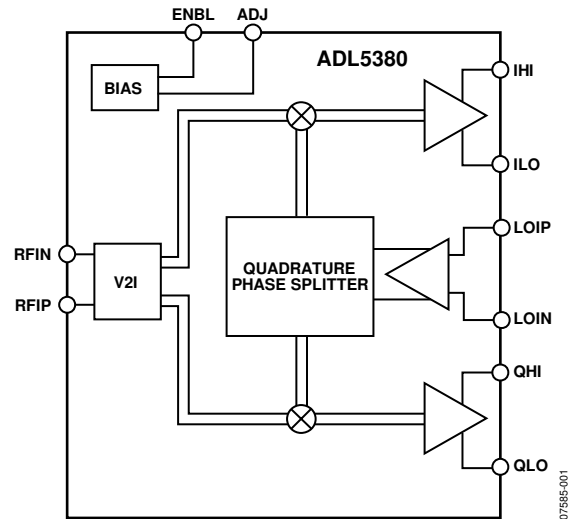


Figure 1.

The fully balanced design minimizes effects from second-order distortion. The leakage from the LO port to the RF port is <math><-50\text{ dBm}</math>. Differential dc offsets at the I and Q outputs are typically <math><20\text{ mV}</math>. Both of these factors contribute to the excellent IIP2 specification, which is >65 dBm.

The **ADL5380** operates off a single 4.75 V to 5.25 V supply. The supply current is adjustable by placing an external resistor from the ADJ pin to either the positive supply, V_s , (to increase supply current and improve IIP3) or to ground (which decreases supply current at the expense of IIP3).

The **ADL5380** is fabricated using the Analog Devices, Inc., advanced silicon-germanium bipolar process and is available in a 24-lead exposed paddle LFCSP.

Rev. B

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ADL5380* PRODUCT PAGE QUICK LINKS

Last Content Update: 02/23/2017

COMPARABLE PARTS

View a parametric search of comparable parts.

EVALUATION KITS

- AD-FMCOMMS6-EBZ Evaluation Board
- ADL5380 Evaluation Boards
- FPGA Mezzanine Card for Wireless Communications

DOCUMENTATION

Data Sheet

- ADL5380: 400 MHz to 6 GHz Quadrature Demodulator Data Sheet

TOOLS AND SIMULATIONS

- ADIsimPLL™
- ADIsimRF

REFERENCE DESIGNS

- CN0245
- CN0374

REFERENCE MATERIALS

Press

- New PLLs Deliver Widest Frequency Range Coverage and Lowest VCO Phase Noise in a Single Device

Product Selection Guide

- RF Source Booklet

Technical Articles

- Assess Quadrature-Demodulator Noise Figure Using Vector Signal Analysis
- Direct Conversion Receiver Designs Enable Multi-standard/Multi-band Operation
- Semiconductors Simplify Direct-Conversion Design

DESIGN RESOURCES

- adI5380 Material Declaration
- PCN-PDN Information
- Quality And Reliability
- Symbols and Footprints

DISCUSSIONS

View all adI5380 EngineerZone Discussions.

SAMPLE AND BUY

Visit the product page to see pricing options.

TECHNICAL SUPPORT

Submit a technical question or find your regional support number.

DOCUMENT FEEDBACK

Submit feedback for this data sheet.

TABLE OF CONTENTS

Features	1	LO Interface	22
Applications.....	1	V-to-I Converter	22
Functional Block Diagram	1	Mixers	22
General Description	1	Emitter Follower Buffers	22
Revision History	2	Bias Circuit.....	22
Specifications.....	3	Applications Information	23
Absolute Maximum Ratings.....	5	Basic Connections.....	23
ESD Caution.....	5	Power Supply.....	23
Pin Configuration and Function Descriptions.....	6	Local Oscillator and RF Inputs.....	24
Typical Performance Characteristics	7	Baseband Outputs	25
Low Band Operation.....	7	Error Vector Magnitude (EVM) Performance.....	25
Midband Operation	11	Low IF Image Rejection.....	26
High Band Operation	14	Example Baseband Interface.....	27
Distributions for $f_{LO} = 900$ MHz.....	17	Characterization Setups.....	31
Distributions for $f_{LO} = 1900$ MHz.....	18	Evaluation Board	33
Distributions for $f_{LO} = 2700$ MHz.....	19	Thermal Grounding and Evaluation Board Layout.....	35
Distributions for $f_{LO} = 3600$ MHz.....	20	Outline Dimensions	36
Distributions for $f_{LO} = 5800$ MHz.....	21	Ordering Guide	36
Circuit Description.....	22		

REVISION HISTORY

12/14—Rev. A to Rev. B

Changes to Figure 2 and Table 3.....	6
Updated Outline Dimensions	36
Changes to Ordering Guide	36

7/13—Rev. 0 to Rev. A

Changes to Table 2.....	5
Deleted Local Oscillator (LO) Input Section	23
Changed RF Input Section to Local Oscillator and RF Inputs Section.....	24
Added Figure 78, Figure 79, and Figure 82, Renumbered Sequentially.....	24
Added Figure 83 and Figure 84	25
Changes to Evaluation Board Section and Figure 102	33
Changes to Table 5 and Figure 103 Caption	34
Deleted Figure 100, Figure 101, and Figure 102.....	34
Updated Outline Dimensions	36
Changes to Ordering Guide	36

7/09—Revision 0: Initial Version

SPECIFICATIONS

$V_S = 5\text{ V}$, $T_A = 25^\circ\text{C}$, $f_{LO} = 900\text{ MHz}$, $f_{IF} = 4.5\text{ MHz}$, $P_{LO} = 0\text{ dBm}$, $Z_O = 50\ \Omega$, unless otherwise noted. Baseband outputs differentially loaded with $450\ \Omega$. Loss of the balun used to drive the RF port was de-embedded from these measurements.

Table 1.

Parameter	Condition	Min	Typ	Max	Unit
OPERATING CONDITIONS					
LO and RF Frequency Range		0.4		6	GHz
LO INPUT					
Input Return Loss	LOIP, LOIN		-10		dB
LO Input Level	LO driven differentially through a balun at 900 MHz	-6	0	+6	dBm
I/Q BASEBAND OUTPUTS					
Voltage Conversion Gain	QHI, QLO, IHI, ILO		6.9		dB
	450 Ω differential load on I and Q outputs at 900 MHz		5.9		dB
	200 Ω differential load on I and Q outputs at 900 MHz		390		MHz
Demodulation Bandwidth	1 V p-p signal, 3 dB bandwidth		0.2		Degrees
Quadrature Phase Error	At 900 MHz		0.07		dB
I/Q Amplitude Imbalance			± 10		mV
Output DC Offset (Differential)	0 dBm LO input at 900 MHz				
Output Common Mode	Dependent on ADJ pin setting				
	$V_{ADJ} \sim 4\text{ V}$ (set by 1.5 k Ω from ADJ pin to V_S)		$V_S - 2.5$		V
	$V_{ADJ} \sim 4.8\text{ V}$ (set by 200 Ω from ADJ pin to V_S)		$V_S - 2.8$		V
	$V_{ADJ} \sim 2.4\text{ V}$ (ADJ pin open)		$V_S - 1.2$		V
0.1 dB Gain Flatness			37		MHz
Output Swing	Differential 200 Ω load		2		V p-p
Peak Output Current	Each pin		12		mA
POWER SUPPLIES					
Voltage	$V_S = VCC1, VCC2, VCC3$	4.75		5.25	V
Current	1.5 k Ω from ADJ pin to V_S ; ENBL pin low		245		mA
	1.5 k Ω from ADJ pin to V_S ; ENBL pin high		145		mA
ENABLE FUNCTION					
Off Isolation	Pin ENBL		-70		dB
Turn-On Settling Time	ENBL high to low		45		ns
Turn-Off Settling Time	ENBL low to high		950		ns
ENBL High Level (Logic 1)		2.5			V
ENBL Low Level (Logic 0)				1.7	V
DYNAMIC PERFORMANCE at RF = 900 MHz					
Conversion Gain	$V_{ADJ} \sim 4\text{ V}$ (set by 1.5 k Ω from ADJ pin to V_S)		6.9		dB
Input P1dB			11.6		dBm
RF Input Return Loss	RFIP, RFIN driven differentially through a balun		-19		dB
Second-Order Input Intercept (IIP2)	-5 dBm each input tone		68		dBm
Third-Order Input Intercept (IIP3)	-5 dBm each input tone		29.7		dBm
LO to RF	RFIN, RFIP terminated in 50 Ω		-52		dBm
RF to LO	LOIN, LOIP terminated in 50 Ω		-67		dBc
IQ Magnitude Imbalance			0.07		dB
IQ Phase Imbalance			0.2		Degrees
Noise Figure			10.9		dB
Noise Figure Under Blocking Conditions	With a -5 dBm input interferer 5 MHz away		13.1		dB

Parameter	Condition	Min	Typ	Max	Unit
DYNAMIC PERFORMANCE at RF = 1900 MHz					
	$V_{ADJ} \sim 4\text{ V}$ (set by 1.5 k Ω from ADJ pin to V_S)				
Conversion Gain			6.8		dB
Input P1dB			11.6		dBm
RF Input Return Loss	RFIP, RFIN driven differentially through a balun		-13		dB
Second-Order Input Intercept (IIP2)	-5 dBm each input tone		61		dBm
Third-Order Input Intercept (IIP3)	-5 dBm each input tone		27.8		dBm
LO to RF	RFIN, RFIP terminated in 50 Ω		-49		dBm
RF to LO	LOIN, LOIP terminated in 50 Ω		-77		dBc
IQ Magnitude Imbalance			0.07		dB
IQ Phase Imbalance			0.25		Degrees
Noise Figure			11.7		dB
Noise Figure Under Blocking Conditions	With a -5 dBm input interferer 5 MHz away		14		dB
DYNAMIC PERFORMANCE at RF = 2700 MHz					
	$V_{ADJ} \sim 4\text{ V}$ (set by 1.5 k Ω from ADJ pin to V_S)				
Conversion Gain			7.4		dB
Input P1dB			11		dBm
RF Input Return Loss	RFIP, RFIN driven differentially through a balun		-10		dB
Second-Order Input Intercept (IIP2)	-5 dBm each input tone		54		dBm
Third-Order Input Intercept (IIP3)	-5 dBm each input tone		28		dBm
LO to RF	RFIN, RFIP terminated in 50 Ω		-49		dBm
RF to LO	LOIN, LOIP terminated in 50 Ω		-73		dBc
IQ Magnitude Imbalance			0.07		dB
IQ Phase Imbalance			0.5		Degrees
Noise Figure			12.3		dB
DYNAMIC PERFORMANCE at RF = 3600 MHz					
	$V_{ADJ} \sim 4.8\text{ V}$ (set by 200 Ω from ADJ pin to V_S)				
Conversion Gain			6.3		dB
Input P1dB			9.6		dBm
RF Input Return Loss	RFIP, RFIN driven differentially through a balun		-11		dB
Second-Order Input Intercept (IIP2)	-5 dBm each input tone		48		dBm
Third-Order Input Intercept (IIP3)	-5 dBm each input tone		21		dBm
LO to RF	RFIN, RFIP terminated in 50 Ω		-46		dBm
RF to LO	LOIN, LOIP terminated in 50 Ω		-72		dBc
IQ Magnitude Imbalance			0.14		dB
IQ Phase Imbalance			1.1		Degrees
Noise Figure			14.2		dB
Noise Figure Under Blocking Conditions	With a -5 dBm input interferer 5 MHz away		16.2		dB
DYNAMIC PERFORMANCE at RF = 5800 MHz					
	$V_{ADJ} \sim 2.4\text{ V}$ (ADJ pin left open)				
Conversion Gain			5.8		dB
Input P1dB			8.2		dBm
RF Input Return Loss	RFIP, RFIN driven differentially through a balun		-7.5		dB
Second-Order Input Intercept (IIP2)	-5 dBm each input tone		44		dBm
Third-Order Input Intercept (IIP3)	-5 dBm each input tone		20.6		dBm
LO to RF	RFIN, RFIP terminated in 50 Ω		-47		dBm
RF to LO	LOIN, LOIP terminated in 50 Ω		-62		dBc
IQ Magnitude Imbalance			0.07		dB
IQ Phase Imbalance			-1.25		Degrees
Noise Figure			15.5		dB
Noise Figure Under Blocking Conditions	With a -5 dBm input interferer 5 MHz away		18.9		dB

ABSOLUTE MAXIMUM RATINGS

Table 2.

Parameter	Rating
Supply Voltage: VCC1, VCC2, VCC3	5.5 V
LO Input Power	13 dBm (re: 50 Ω)
RF Input Power	15 dBm (re: 50 Ω)
Internal Maximum Power Dissipation	1370 mW
θ_{JA} ¹	53°C/W
θ_{JC}	2.5°C/W
Maximum Junction Temperature	150°C
Operating Temperature Range	-40°C to +85°C
Storage Temperature Range	-65°C to +125°C

¹ Per JEDEC standard JESD 51-2. For information on optimizing thermal impedance, see the Thermal Grounding and Evaluation Board Layout section.

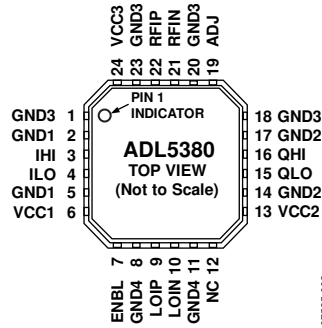
Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS



NOTES

1. NC = NO CONNECT. DO NOT CONNECT TO THIS PIN.
2. THE EXPOSED PAD SHOULD BE CONNECTED TO A LOW IMPEDANCE THERMAL AND ELECTRICAL GROUND PLANE.

Figure 2. Pin Configuration

Table 3. Pin Function Descriptions

Pin No.	Mnemonic	Description
1, 2, 5, 8, 11, 14, 17, 18, 20, 23	GND1, GND2, GND3, GND4	Ground Connect.
3, 4, 15, 16	IHI, ILO, QLO, QHI	I Channel and Q Channel Mixer Baseband Outputs. These outputs have a 50 Ω differential output impedance (25 Ω per pin). Each output pair can swing 2 V p-p (differential) into a load of 200 Ω . The output 3 dB bandwidth is ~400 MHz.
6, 13, 24	VCC1, VCC2, VCC3	Supply. Positive supply for LO, IF, biasing, and baseband sections. Decouple these pins to the board ground using the appropriate-sized capacitors.
7	ENBL	Enable Control. When pulled low, the part is fully enabled; when pulled high, the part is partially powered down and the output is disabled.
9, 10	LOIP, LOIN	Local Oscillator Input. Pins must be ac-coupled. A differential drive through a balun is necessary to achieve optimal performance. Recommended balun is the Mini-Circuits® TC1-1-13 for lower frequencies, the Johanson Technology 3600 balun for midband frequencies, and the Johanson Technology 5400 balun for high band frequencies. Balun choice depends on the desired frequency range of operation.
12	NC	No Connect. Do not connect to this pin.
19	ADJ	A resistor to V_s that optimizes third-order intercept. For operation <3 GHz, $R_{ADJ} = 1.5$ k Ω . For operation from 3 GHz to 4 GHz, $R_{ADJ} = 200$ Ω . For operation >5 GHz, $R_{ADJ} =$ open. See the Circuit Description section for more details.
21, 22	RFIN, RFIP	RF Input. A single-ended 50 Ω signal can be applied differentially to the RF inputs through a 1:1 balun. Recommended balun is the Mini-Circuits TC1-1-13 for lower frequencies, the Johanson Technology 3600 balun for midband frequencies, and the Johanson Technology 5400 balun for high band frequencies. Balun choice depends on the desired frequency range of operation.
	EP	Exposed Pad. The exposed pad should be connected to a low impedance thermal and electrical ground plane.

TYPICAL PERFORMANCE CHARACTERISTICS

$V_S = 5\text{ V}$, $T_A = 25^\circ\text{C}$, LO drive level = 0 dBm, RF input balun loss is de-embedded, unless otherwise noted.

LOW BAND OPERATION

RF = 400 MHz to 3 GHz; Mini-Circuits TC1-1-13 balun on LO and RF inputs, 1.5 k Ω from the ADJ pin to V_S .

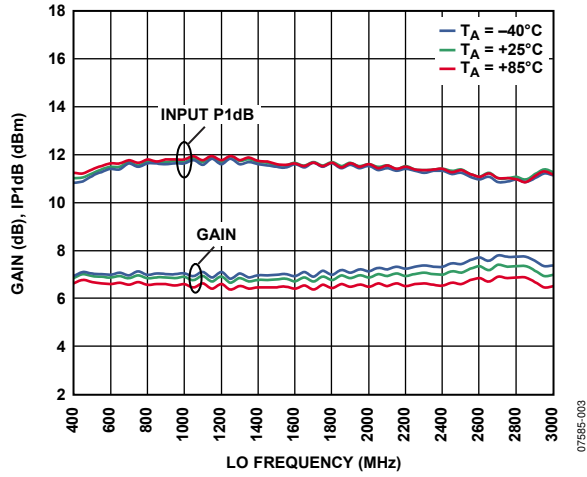


Figure 3. Conversion Gain and Input 1 dB Compression Point (IP1dB) vs. LO Frequency

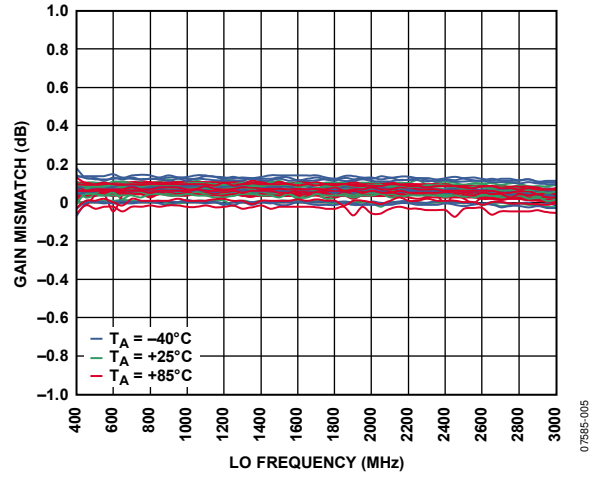


Figure 5. IQ Gain Mismatch vs. LO Frequency

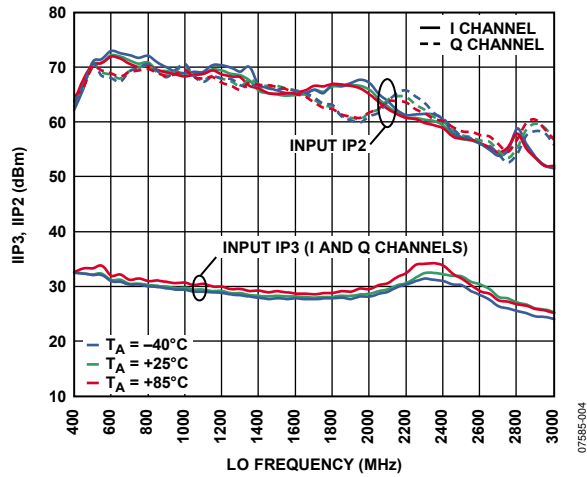


Figure 4. Input Third-Order Intercept (IIP3) and Input Second-Order Intercept Point (IIP2) vs. LO Frequency

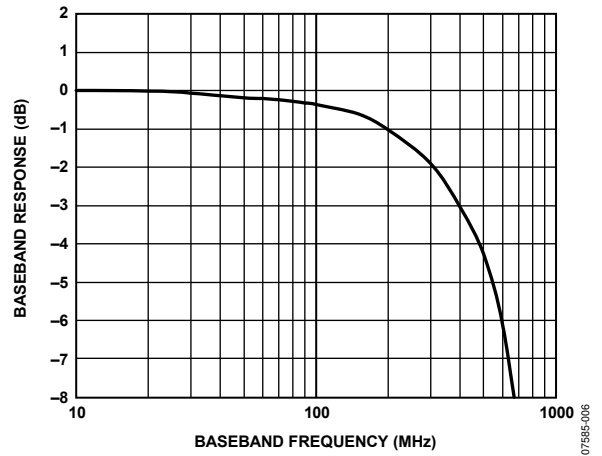


Figure 6. Normalized IQ Baseband Frequency Response

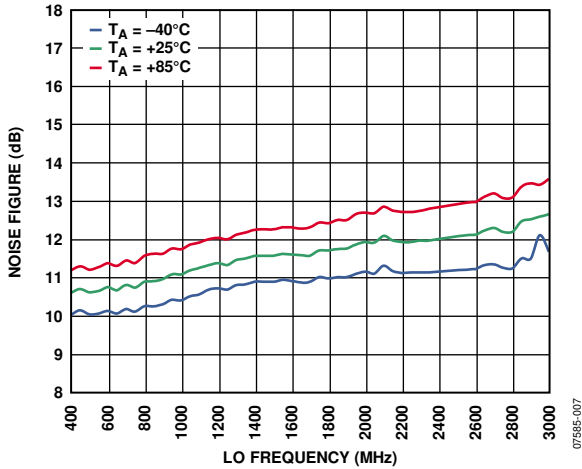


Figure 7. Noise Figure vs. LO Frequency

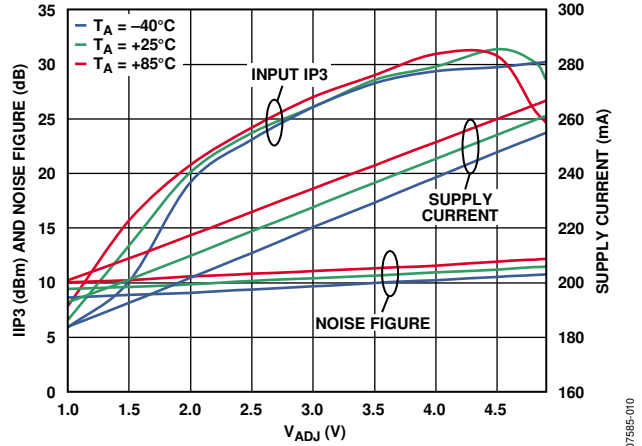


Figure 10. IIP3, Noise Figure, and Supply Current vs. V_{ADJ} , $f_{LO} = 900$ MHz

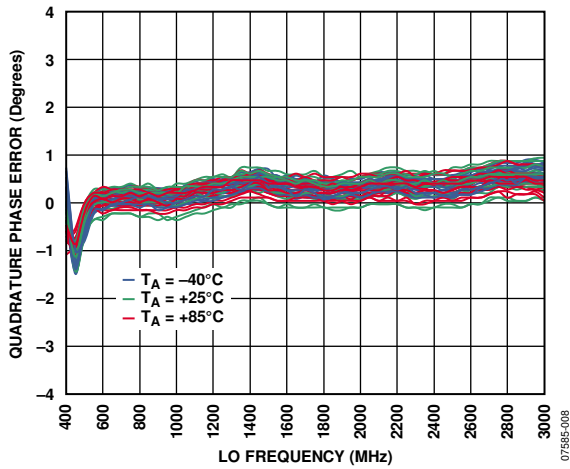


Figure 8. IQ Quadrature Phase Error vs. LO Frequency

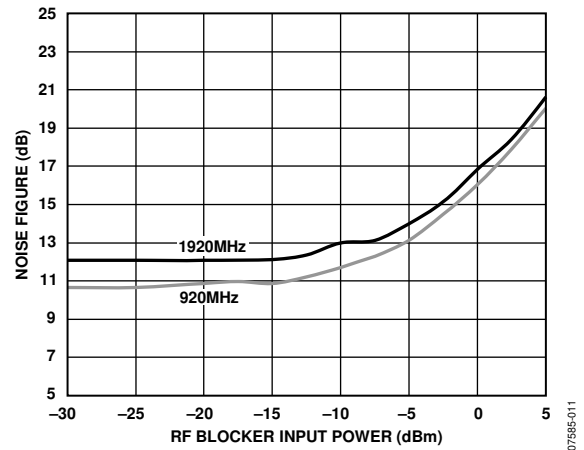


Figure 11. Noise Figure vs. Input Blocker Level, $f_{LO} = 900$ MHz, $f_{LO} = 1900$ MHz (RF Blocker 5 MHz Offset)

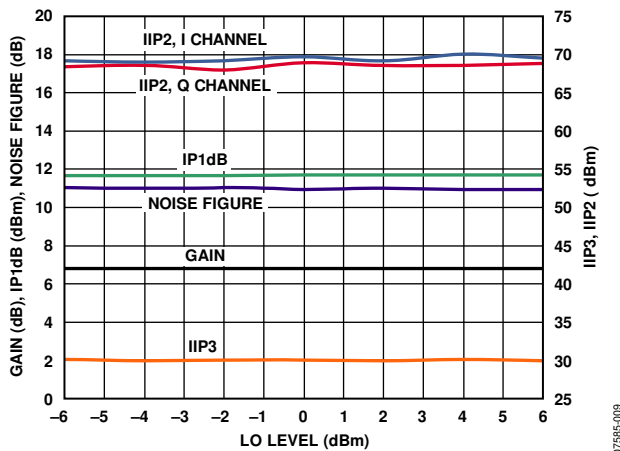


Figure 9. Conversion Gain, IP1dB, Noise Figure, IIP3, and IIP2 vs. LO Level, $f_{LO} = 900$ MHz

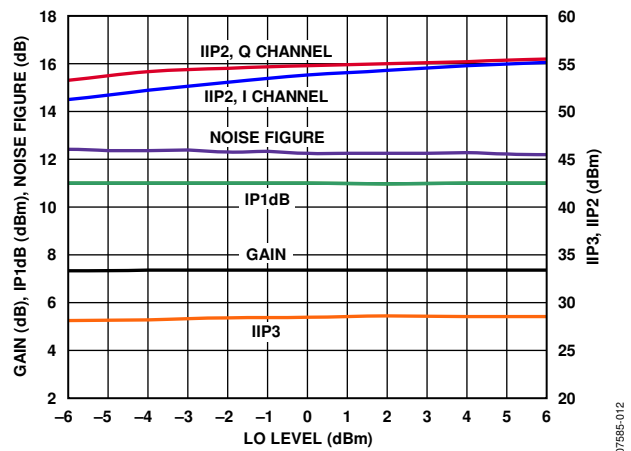


Figure 12. Conversion Gain, IP1dB, Noise Figure, IIP3, and IIP2 vs. LO Level, $f_{LO} = 2700$ MHz

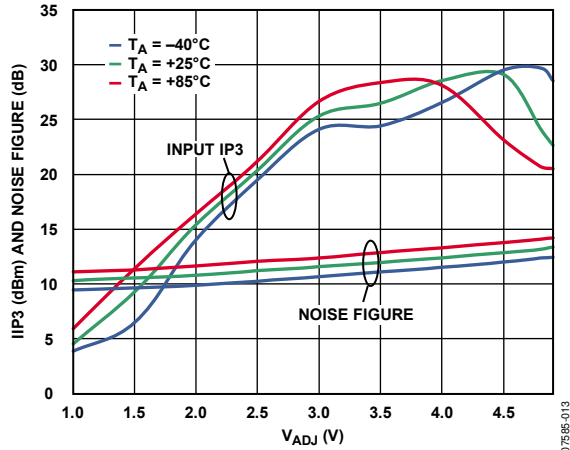


Figure 13. IIP3 and Noise Figure vs. V_{ADJ} , $f_{LO} = 2700$ MHz

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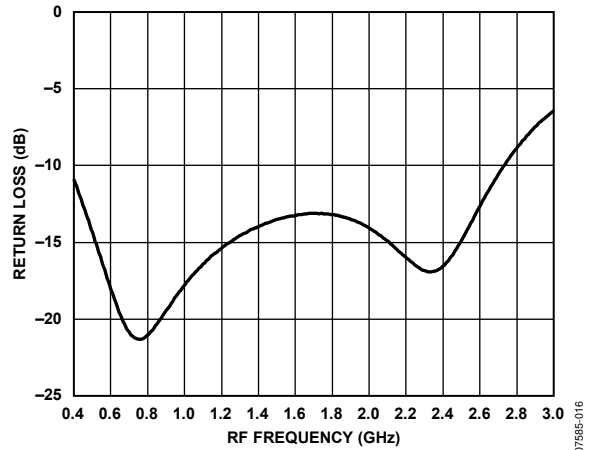


Figure 16. RF Port Return Loss vs. RF Frequency Measured on Characterization Board Through TC1-1-13 Balun

07585-016

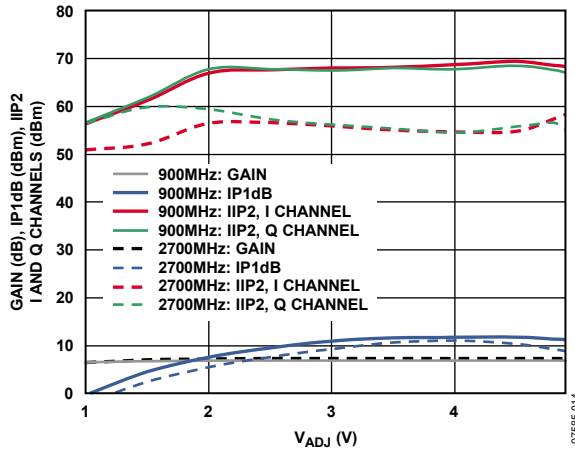


Figure 14. Conversion Gain, IP1dB, and IIP2 vs. V_{ADJ} , $f_{LO} = 900$ MHz, $f_{LO} = 2700$ MHz

07585-014

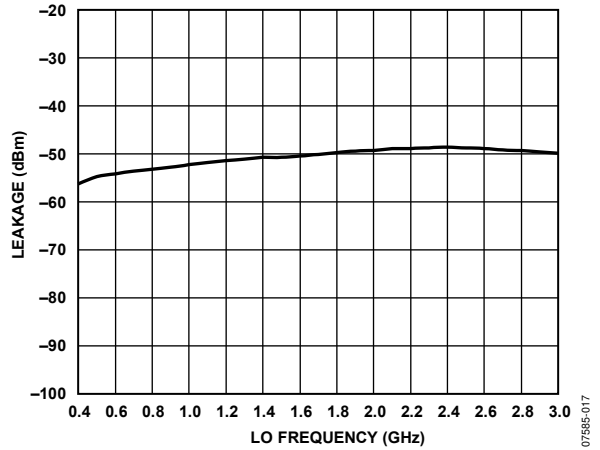


Figure 17. LO-to-RF Leakage vs. LO Frequency

07585-017

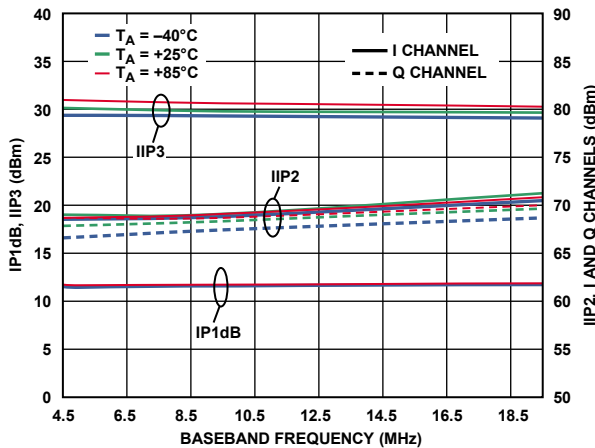


Figure 15. IP1dB, IIP3, and IIP2 vs. Baseband Frequency

07585-015

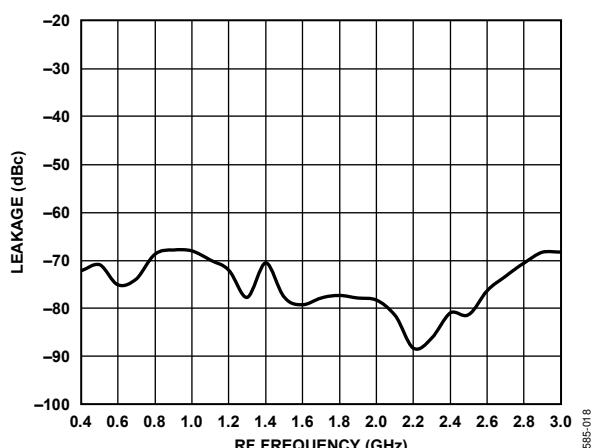


Figure 18. RF-to-LO Leakage vs. RF Frequency

07585-018

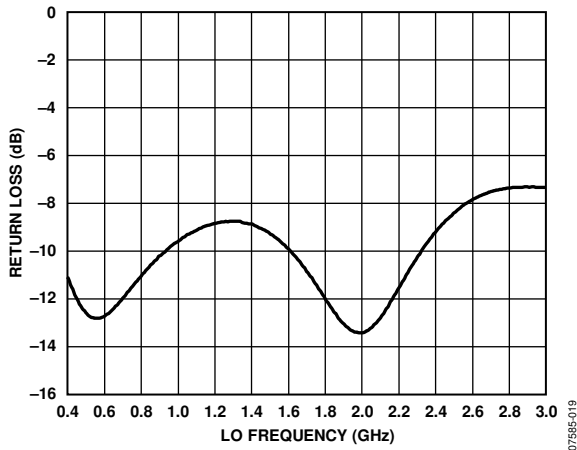


Figure 19. LO Port Return Loss vs. LO Frequency Measured on Characterization Board Through TC1-1-13 Balun

MIDBAND OPERATION

RF = 3 GHz to 4 GHz; Johanson Technology 3600BL14M050T balun on LO and RF inputs, 200 Ω from V_{ADJ} to V_S.

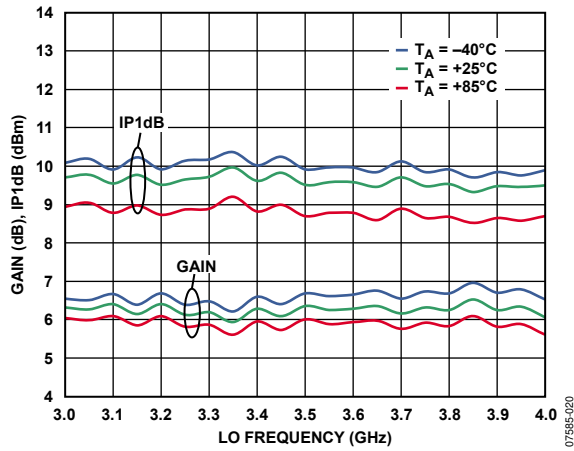


Figure 20. Conversion Gain and Input 1 dB Compression Point (IP1dB) vs. LO Frequency

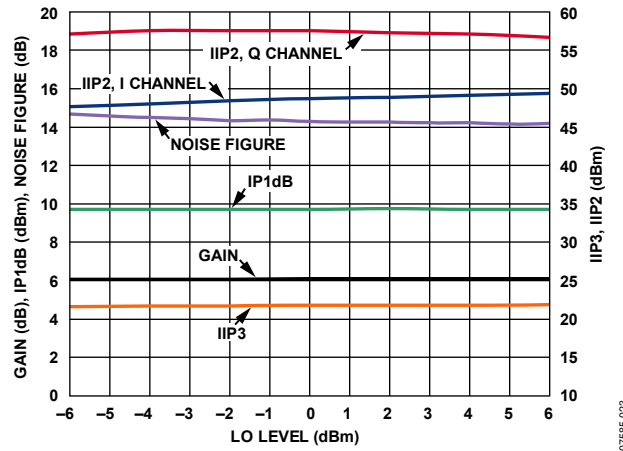


Figure 23. Conversion Gain, IP1dB, Noise Figure, IIP3, and IIP2 vs. LO Level, f_{LO} = 3600 MHz

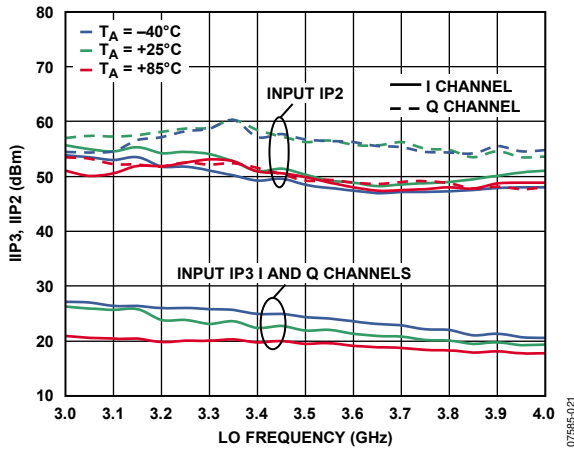


Figure 21. Input Third-Order Intercept (IIP3) and Input Second-Order Intercept Point (IIP2) vs. LO Frequency

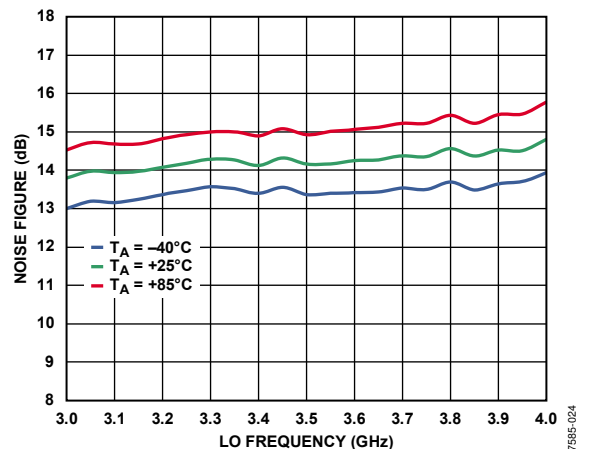


Figure 24. Noise Figure vs. LO Frequency

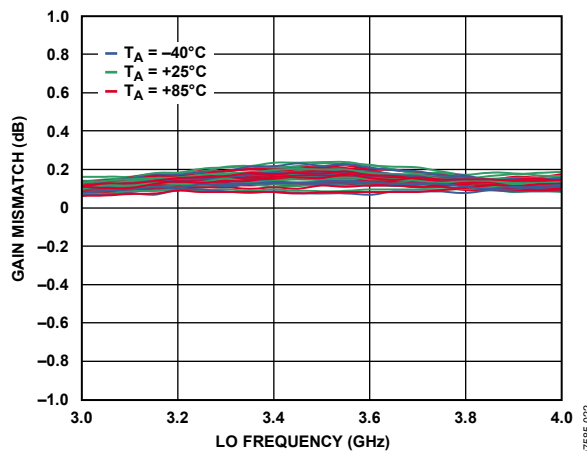


Figure 22. IQ Gain Mismatch vs. LO Frequency

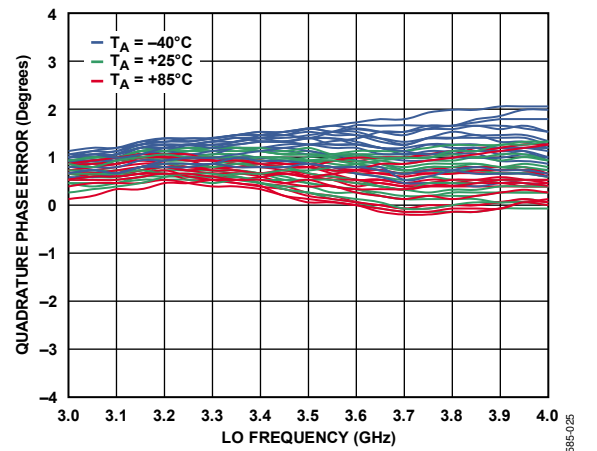
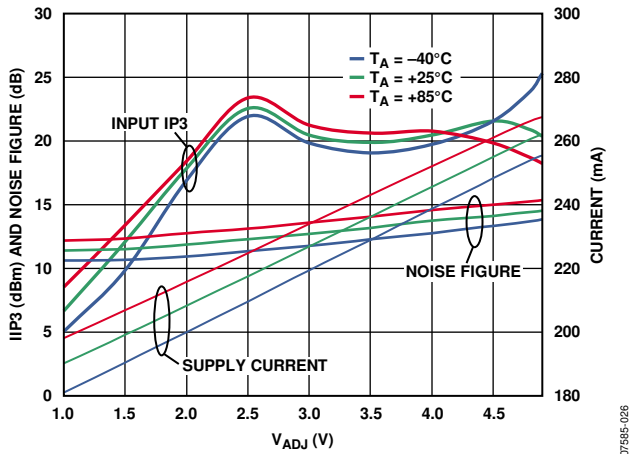
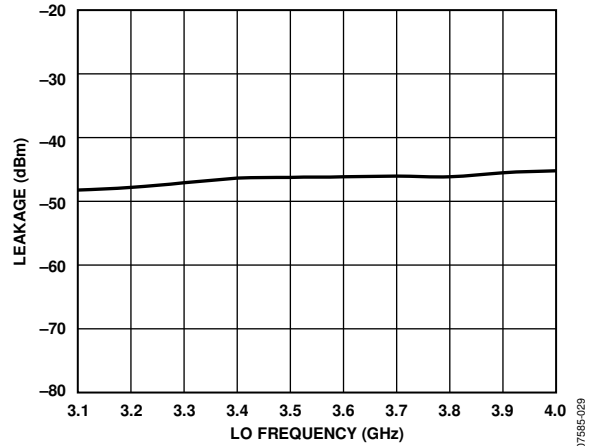


Figure 25. IQ Quadrature Phase Error vs. LO Frequency



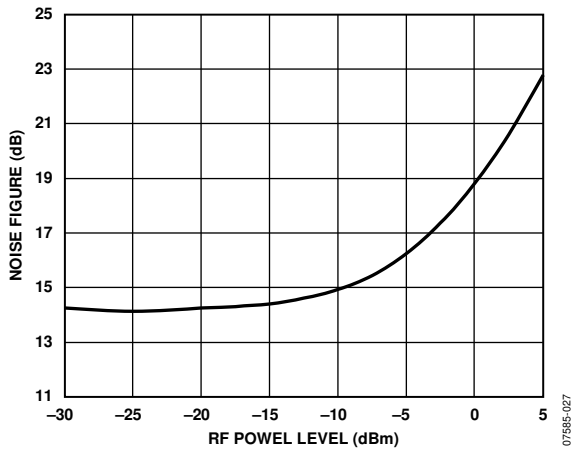
07585-026

Figure 26. IIP3, Noise Figure, and Supply Current vs. V_{ADJ} , $f_{LO} = 3600$ MHz



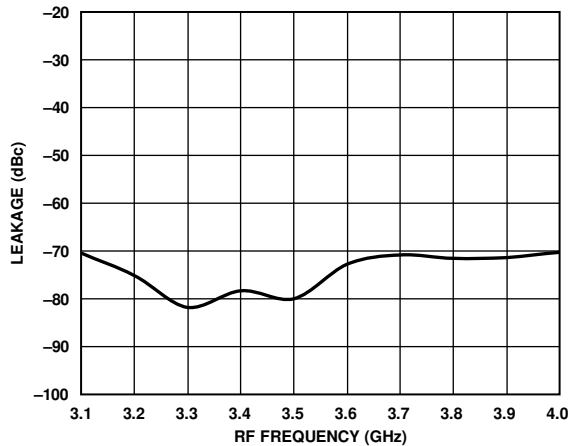
07585-029

Figure 29. LO-to-RF Leakage vs. LO Frequency



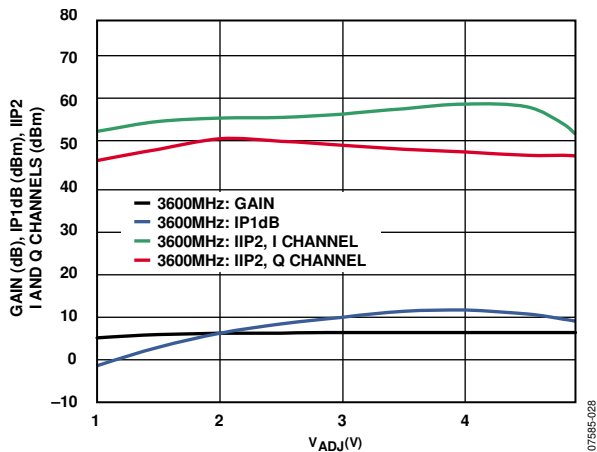
07585-027

Figure 27. Noise Figure vs. Input Blocker Level, $f_{LO} = 3600$ MHz (RF Blocker 5 MHz Offset)



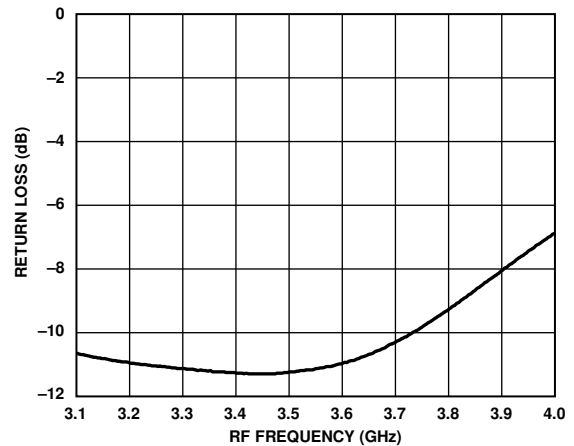
07585-030

Figure 30. RF-to-LO Leakage vs. RF Frequency



07585-028

Figure 28. Conversion Gain, IP1dB, and IIP2 vs. V_{ADJ} , $f_{LO} = 3600$ MHz



07585-031

Figure 31. RF Port Return Loss vs. RF Frequency Measured on Characterization Board Through Johanson Technology 3600 Balun

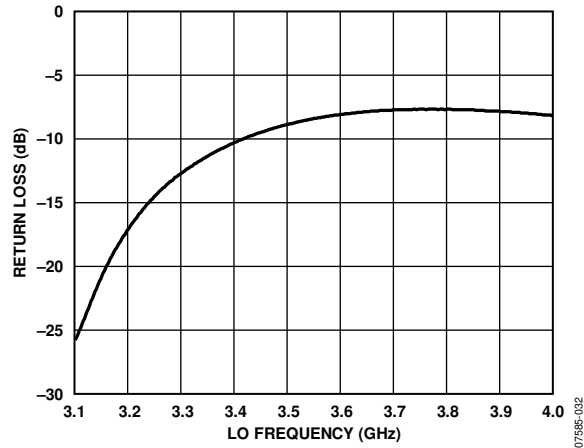


Figure 32. LO Port Return Loss vs. LO Frequency Measured on Characterization Board Through Johanson Technology 3600 Balun

HIGH BAND OPERATION

RF = 5 GHz to 6 GHz; Johanson Technology 5400BL15B050E balun on LO and RF inputs, the ADJ pin is open.

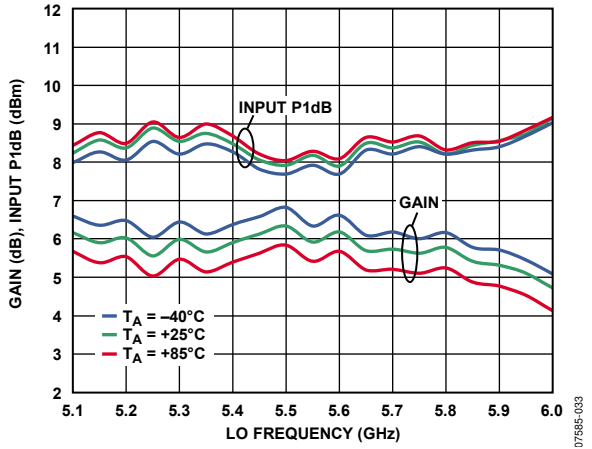


Figure 33. Conversion Gain and Input 1 dB Compression Point (IP1dB) vs. LO Frequency

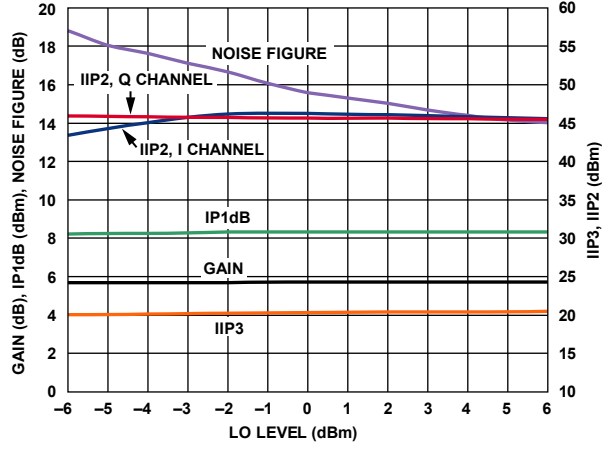


Figure 36. Conversion Gain, IP1dB, Noise Figure, IIP3, and IIP2 vs. LO Level, $f_{LO} = 5800$ MHz

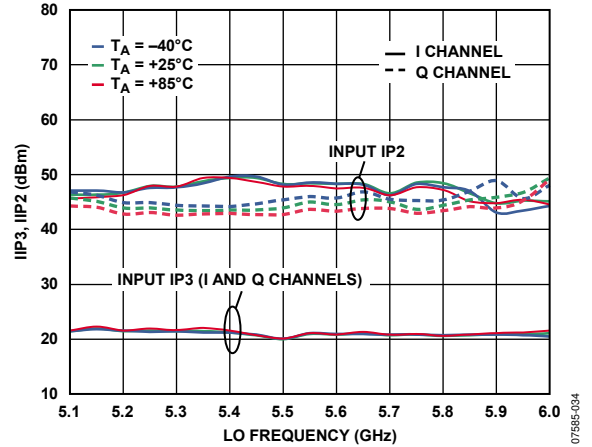


Figure 34. Input Third-Order Intercept (IIP3) and Input Second-Order Intercept Point (IIP2) vs. LO Frequency

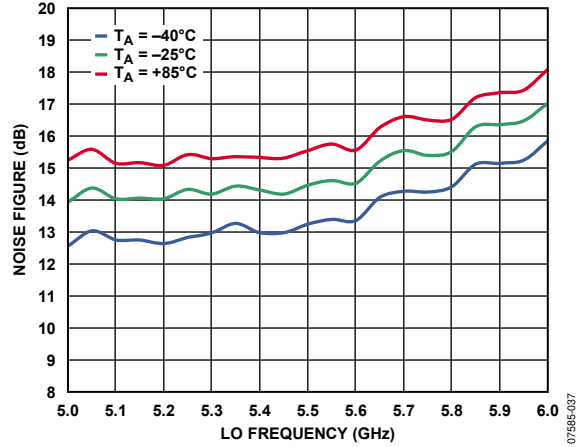


Figure 37. Noise Figure vs. LO Frequency

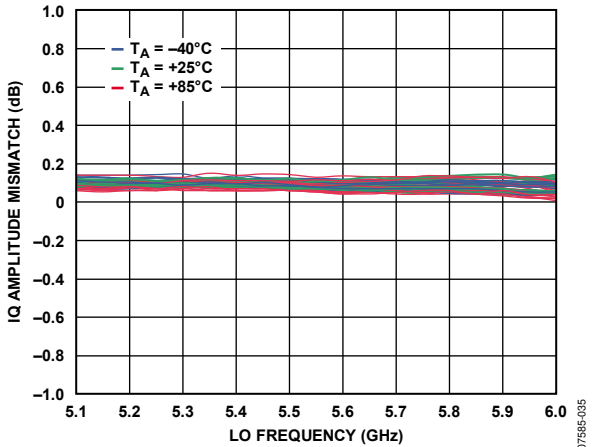


Figure 35. IQ Gain Mismatch vs. LO Frequency

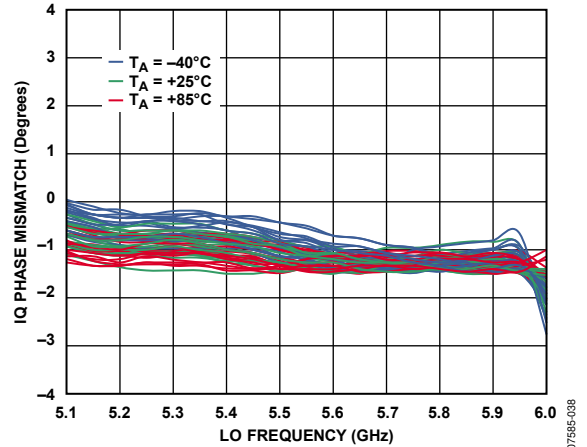


Figure 38. IQ Quadrature Phase Error vs. LO Frequency

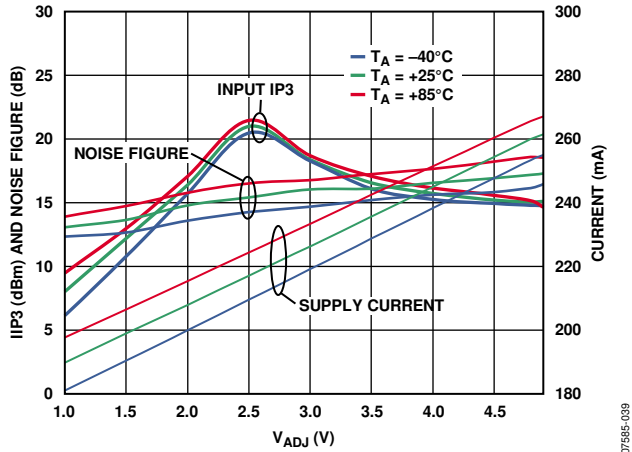


Figure 39. IIP3, Noise Figure, and Supply Current vs. V_{ADJ} , $f_{LO} = 5800$ MHz

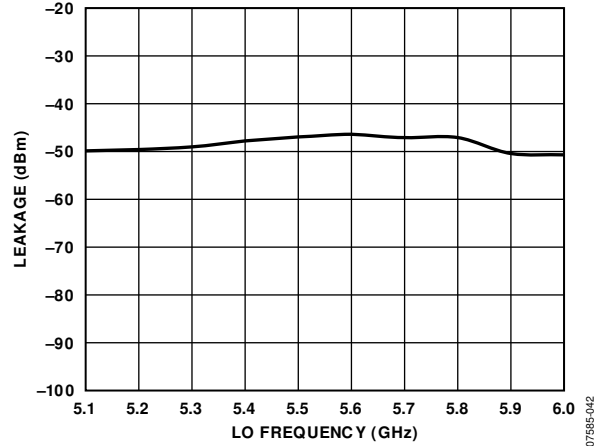


Figure 42. LO-to-RF Leakage vs. LO Frequency

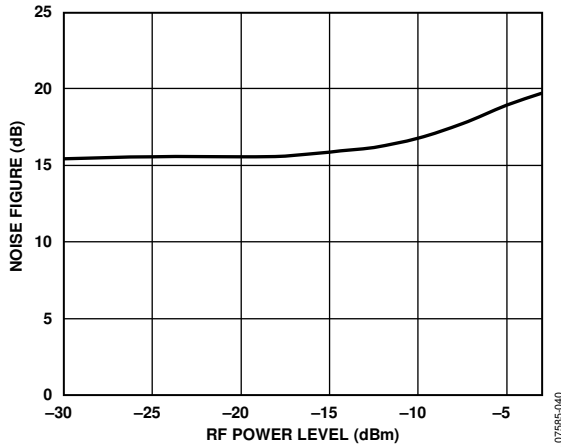


Figure 40. Noise Figure vs. Input Blocker Level, $f_{LO} = 5800$ MHz (RF Blocker 5 MHz Offset)

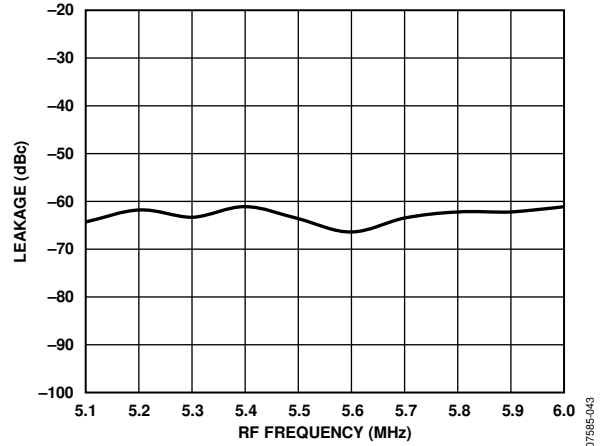


Figure 43. RF-to-LO Leakage vs. RF Frequency

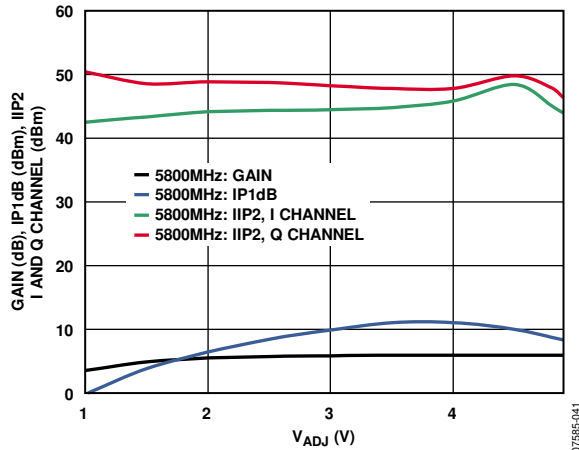


Figure 41. Conversion Gain, IP1dB, and IIP2 vs. V_{ADJ} , R_{BIAS} , $f_{LO} = 5800$ MHz

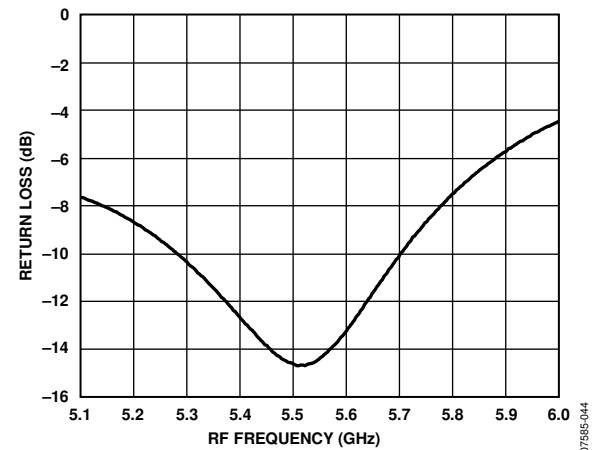


Figure 44. RF Port Return Loss vs. RF Frequency Measured on Characterization Board Through Johanson Technology 5400 Balun

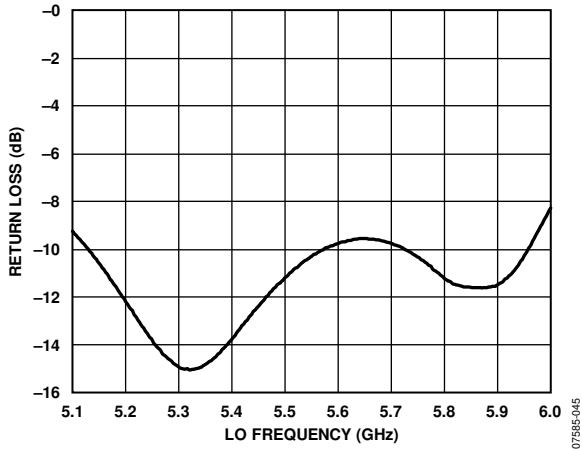


Figure 45. LO Port Return Loss vs. LO Frequency Measured on Characterization Board Through Johanson Technology 5400 Balun

DISTRIBUTIONS FOR $f_{LO} = 900$ MHz

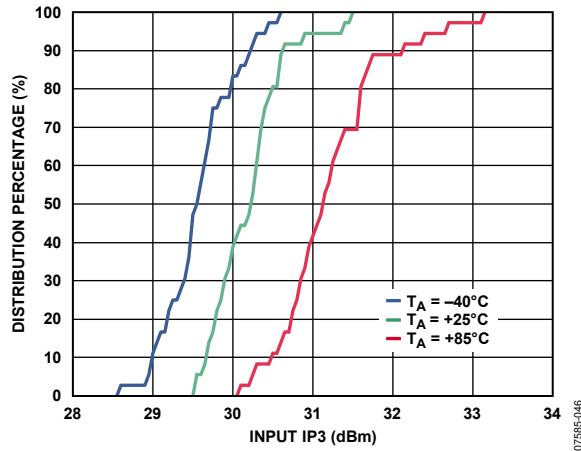


Figure 46. IIP3 Distributions

07985-046

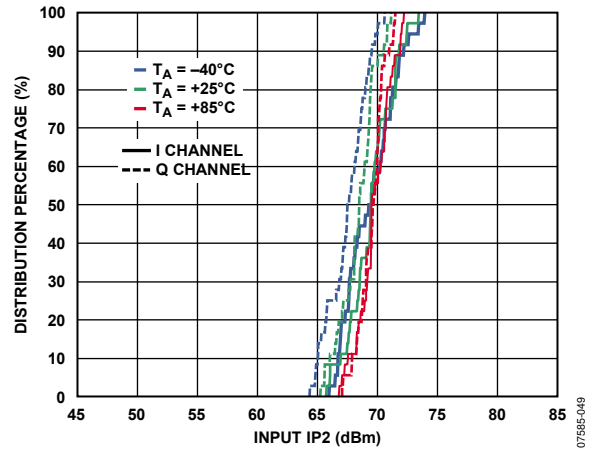


Figure 49. IIP2 Distributions for I Channel and Q Channel

07985-049

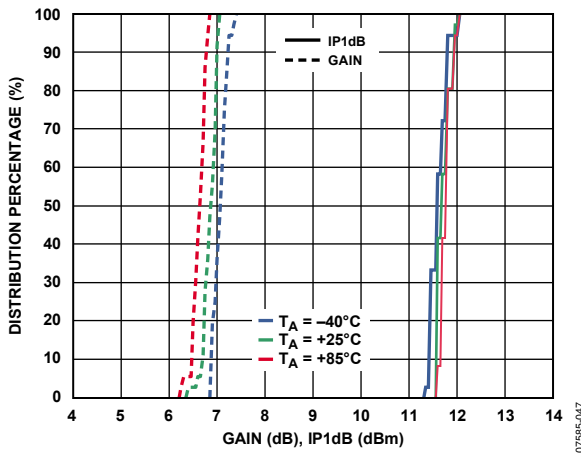


Figure 47. Gain and IP1dB Distributions

07985-047

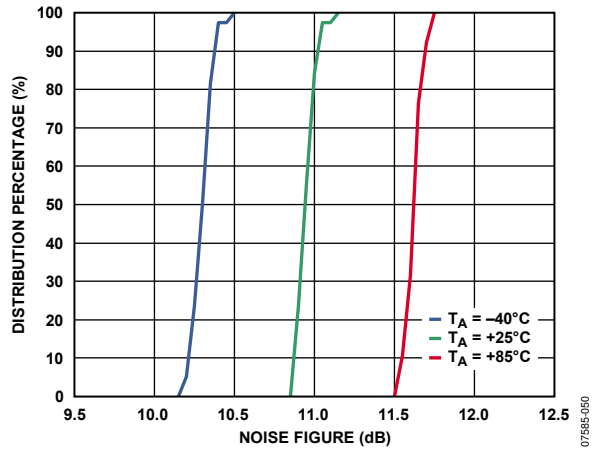


Figure 50. Noise Figure Distributions

07985-050

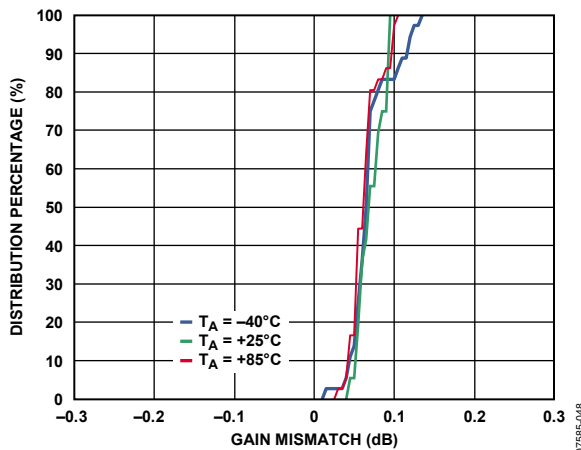


Figure 48. IQ Gain Mismatch Distributions

07985-048

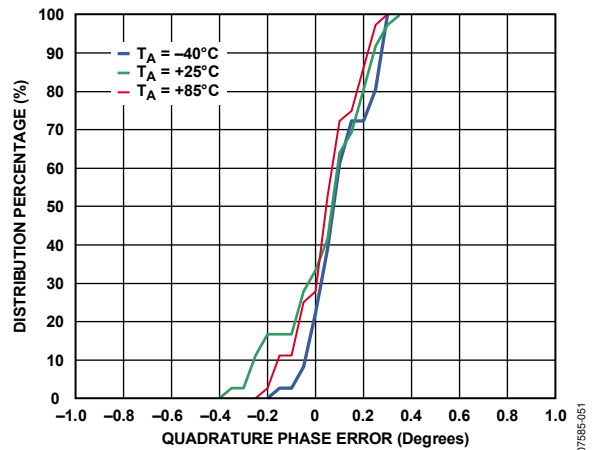


Figure 51. IQ Quadrature Phase Error Distributions

07985-051

DISTRIBUTIONS FOR $f_{LO} = 1900$ MHz

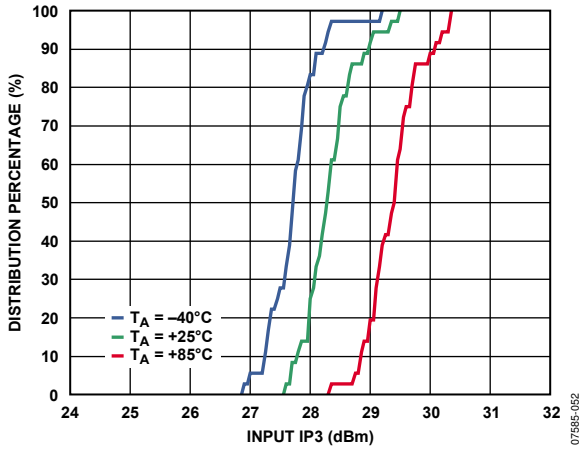


Figure 52. IIP3 Distributions

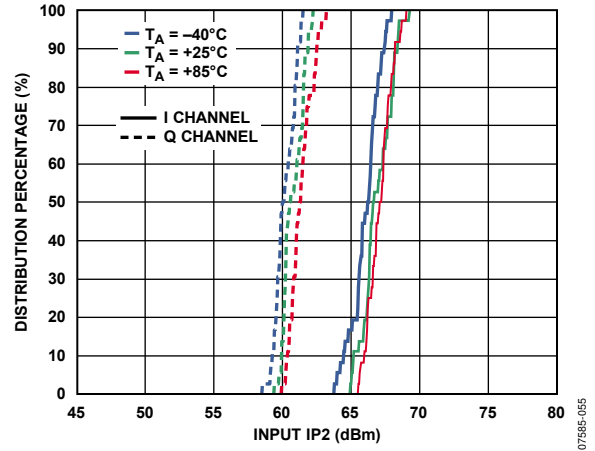


Figure 55. IIP2 Distributions for I Channel and Q Channel

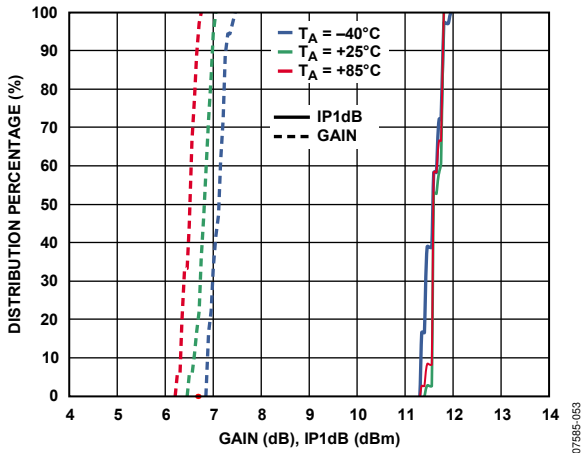


Figure 53. Gain and IP1dB Distributions

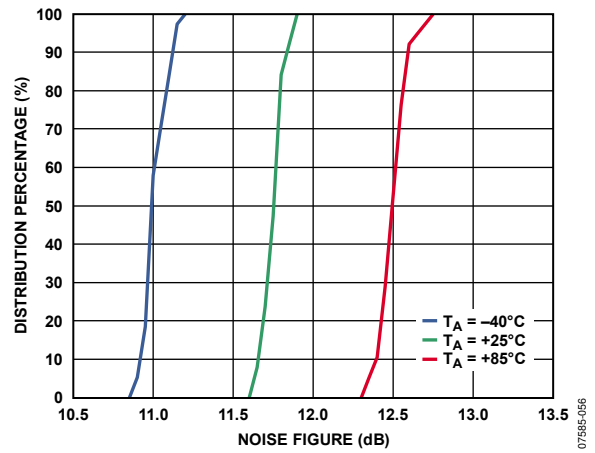


Figure 56. Noise Figure Distributions

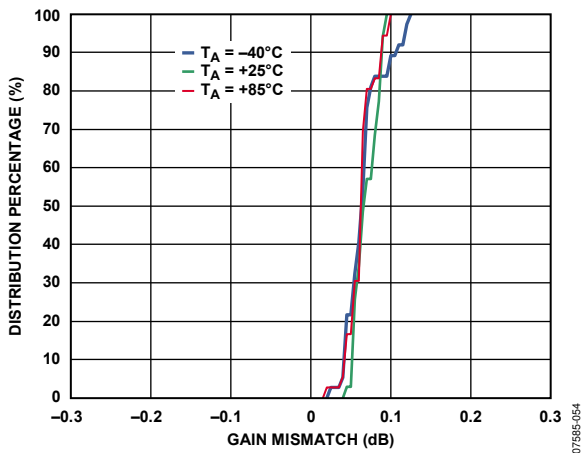


Figure 54. IQ Gain Mismatch Distributions

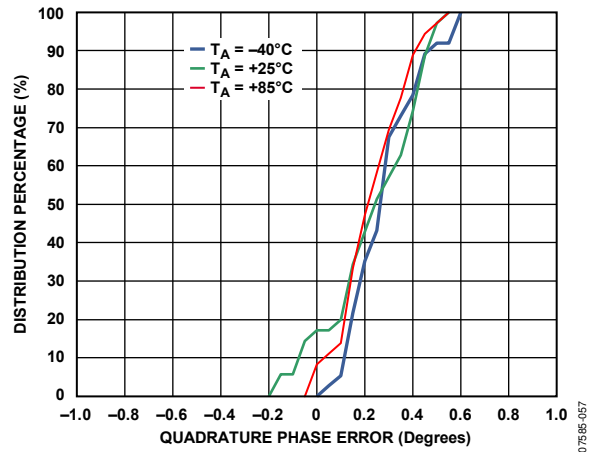


Figure 57. IQ Quadrature Phase Error Distributions

DISTRIBUTIONS FOR $f_{LO} = 2700$ MHz

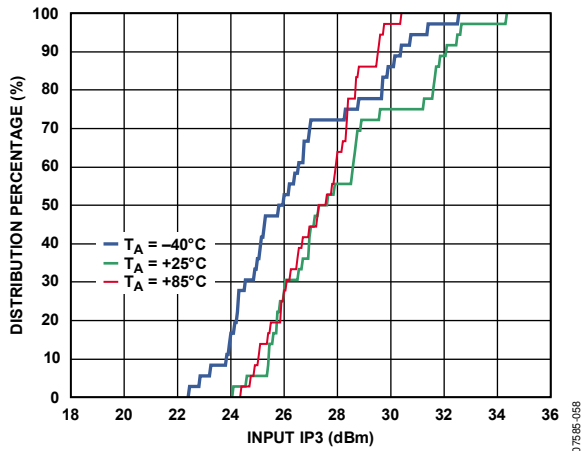


Figure 58. IIP3 Distributions

07595-058

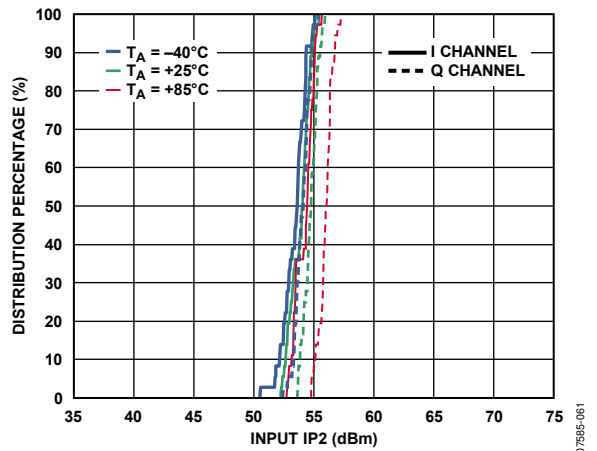


Figure 61. IIP2 Distributions for I Channel and Q Channel

07595-061

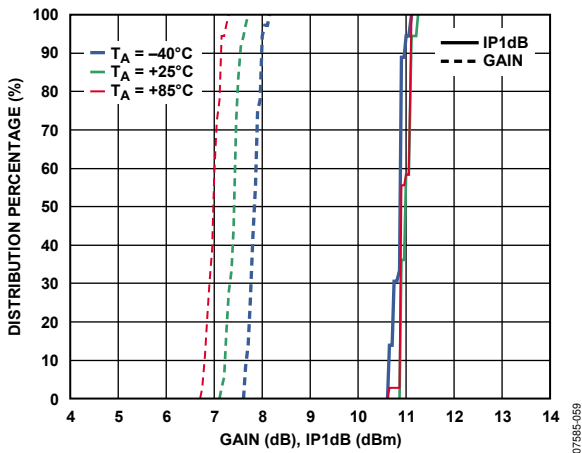


Figure 59. Gain and IP1dB Distributions

07595-059

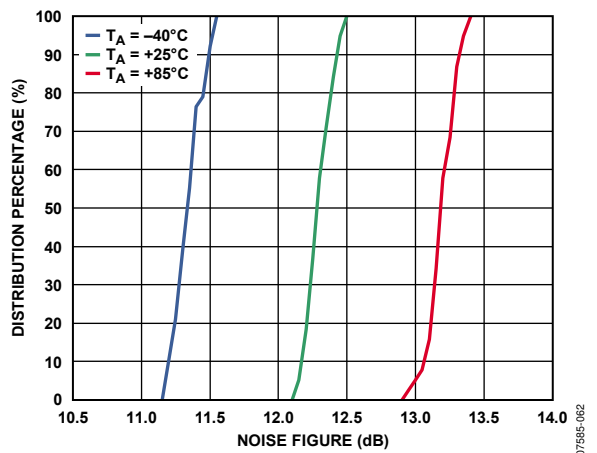


Figure 62. Noise Figure Distributions

07595-062

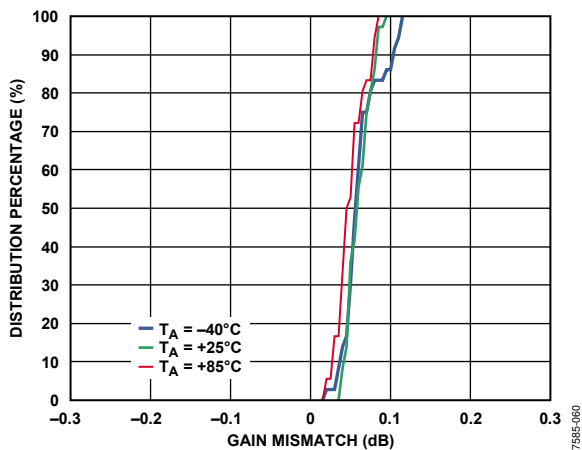


Figure 60. IQ Gain Mismatch Distributions

07595-060

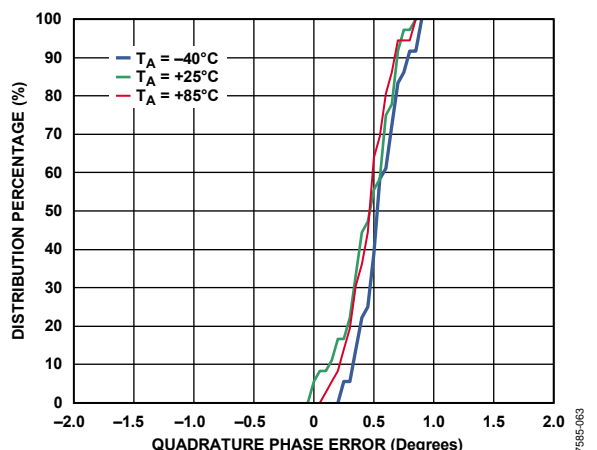


Figure 63. IQ Quadrature Phase Error Distributions

07595-063

DISTRIBUTIONS FOR $f_{LO} = 3600$ MHz

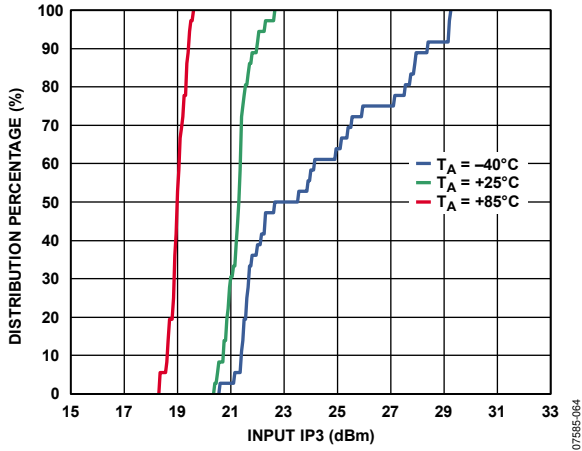


Figure 64. IIP3 Distributions

07595-064

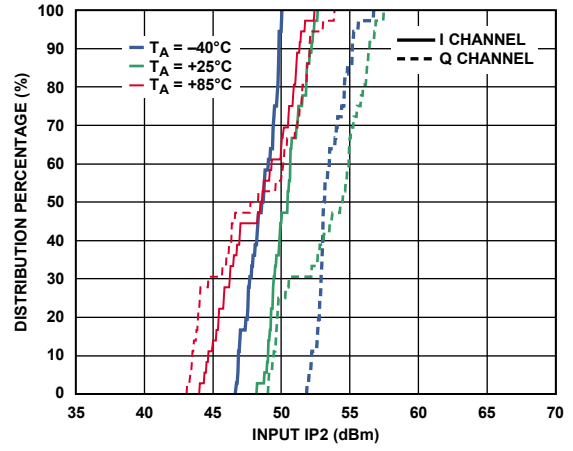


Figure 67. IIP2 Distributions for I Channel and Q Channel

07595-067

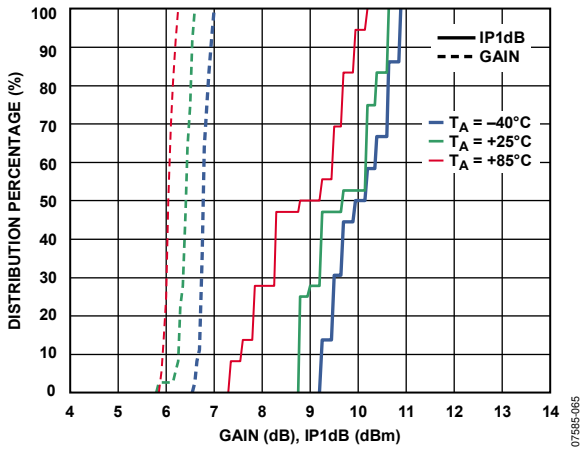


Figure 65. Gain and IP1dB Distributions

07595-065

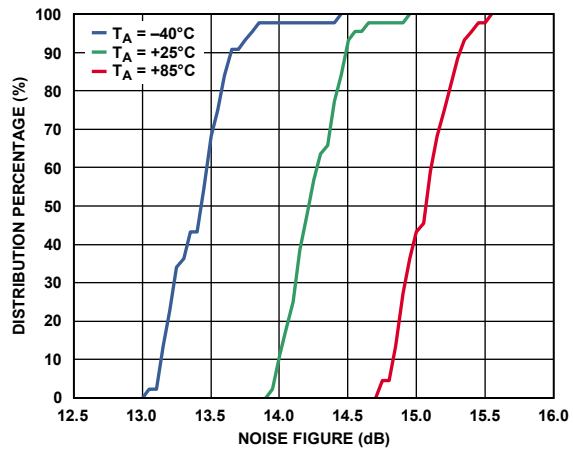


Figure 68. Noise Figure Distributions

07595-068

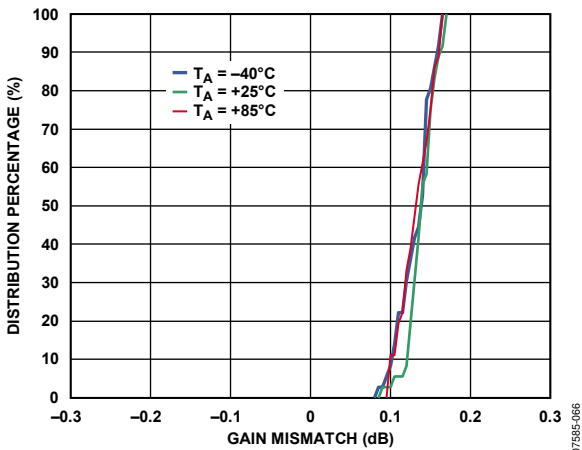


Figure 66. IQ Gain Mismatch Distributions

07595-066

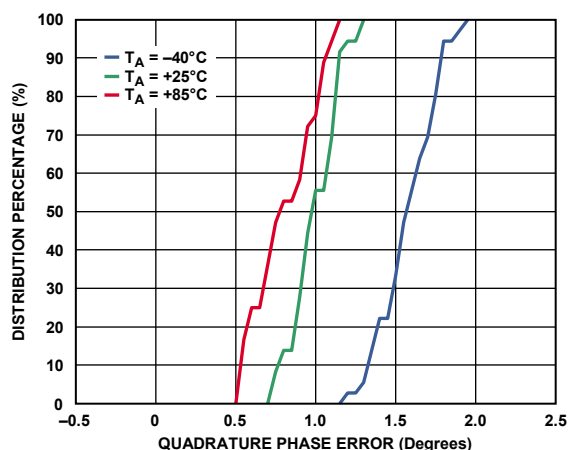


Figure 69. IQ Quadrature Phase Error Distributions

07595-069

DISTRIBUTIONS FOR $f_{LO} = 5800$ MHz

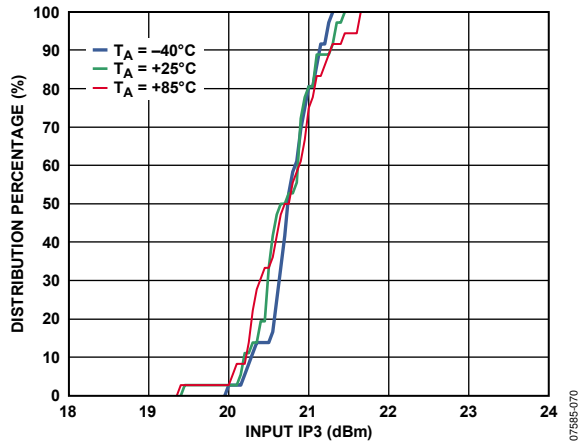


Figure 70. IIP3 Distributions

07585-070

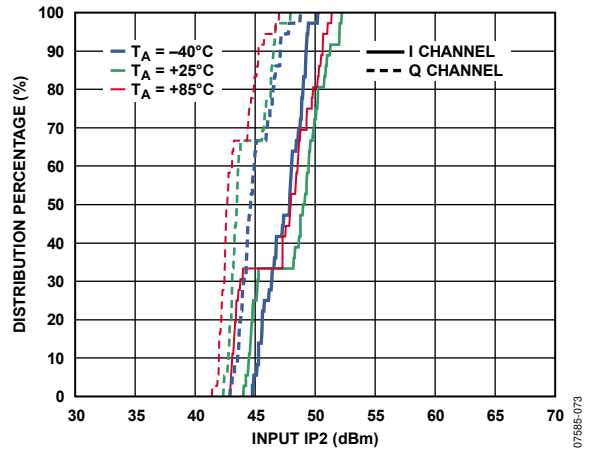


Figure 73. IIP2 Distributions for I Channel and Q Channel

07585-073

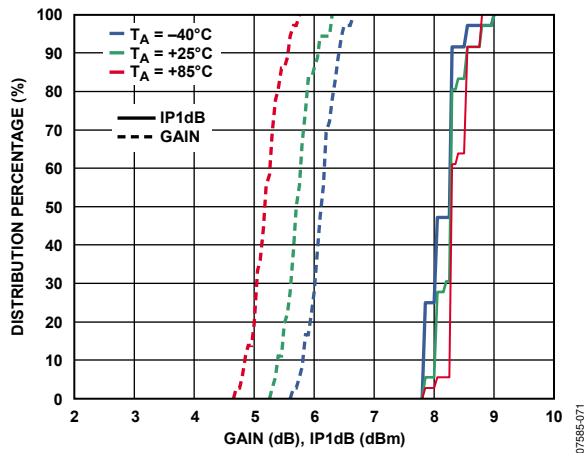


Figure 71. Gain and IP1dB Distributions

07585-071

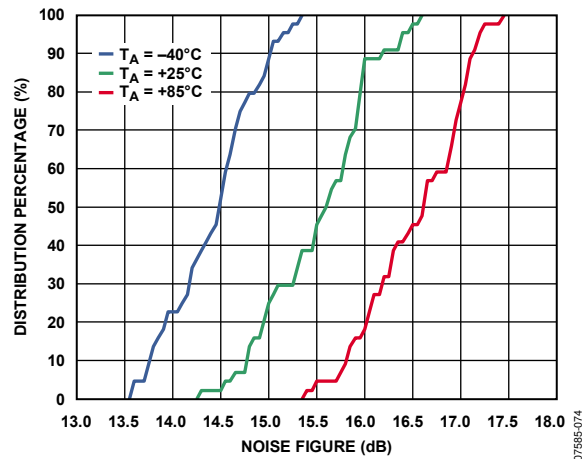


Figure 74. Noise Figure Distributions

07585-074

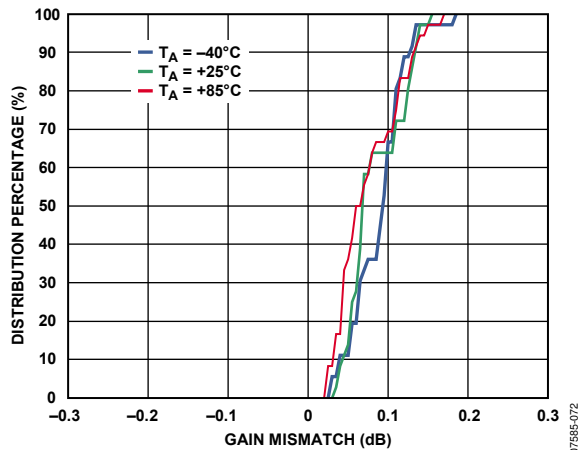


Figure 72. IQ Gain Mismatch Distributions

07585-072

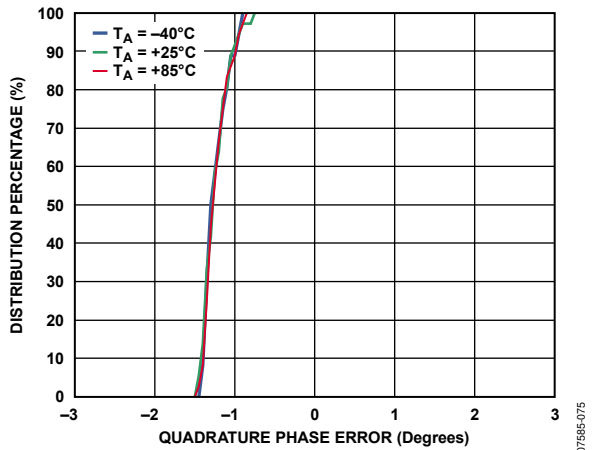


Figure 75. IQ Quadrature Phase Error Distributions

07585-075

CIRCUIT DESCRIPTION

The ADL5380 can be divided into five sections: the local oscillator (LO) interface, the RF voltage-to-current (V-to-I) converter, the mixers, the differential emitter follower outputs, and the bias circuit. A detailed block diagram of the device is shown in Figure 76.

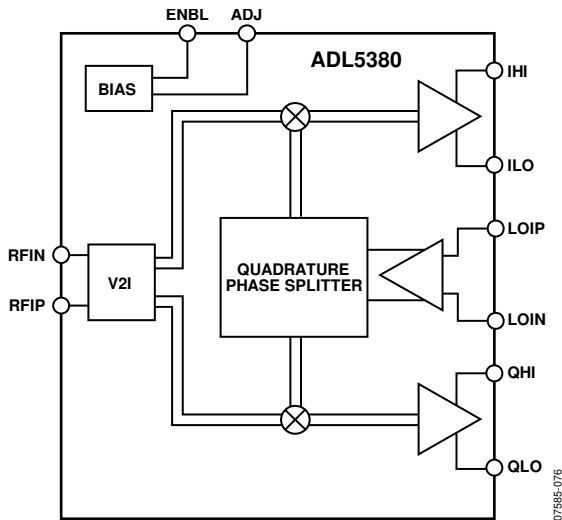


Figure 76. Block Diagram

The LO interface generates two LO signals at 90° of phase difference to drive two mixers in quadrature. RF signals are converted into currents by the V-to-I converters that feed into the two mixers. The differential I and Q outputs of the mixers are buffered via emitter followers. Reference currents to each section are generated by the bias circuit. A detailed description of each section follows.

LO INTERFACE

The LO interface consists of a polyphase quadrature splitter followed by a limiting amplifier. The LO input impedance is set by the polyphase, which splits the LO signal into two differential signals in quadrature. The LO input impedance is nominally 50 Ω. Each quadrature LO signal then passes through a limiting amplifier that provides the mixer with a limited drive signal. For optimal performance, the LO inputs must be driven differentially.

V-TO-I CONVERTER

The differential RF input signal is applied to a V-to-I converter that converts the differential input voltage to output currents. The V-to-I converter provides a differential 50 Ω input impedance. The V-to-I bias current can be adjusted up or down using the ADJ pin (Pin 19). Adjusting the current up improves IIP3 and IP1dB but degrades SSB NF. Adjusting the current down improves SSB NF but degrades IIP3 and IP1dB. The current adjustment can be made by connecting a resistor from the ADJ pin (Pin 19) to V_S to increase the bias current or to ground to decrease the bias current. Table 4 approximately dictates the relationship between the resistor used (R_{ADJ}), the resulting ADJ pin voltage, and the resulting baseband common-mode output voltage.

Table 4. ADJ Pin Resistor Values and Approximate ADJ Pin Voltages

R_{ADJ}	$\sim V_{ADJ}$ (V)	\sim Baseband Common-Mode Output (V)
200 Ω to V_S	4.8	2.2
600 Ω to V_S	4.5	2.3
1.54 kΩ to V_S	4	2.5
3.8 kΩ to V_S	3.5	2.7
10 kΩ to V_S	3	3
Open	2.5	3.2
9 kΩ to GND	2	3.4
3.5 kΩ to GND	1.5	3.6
1.5 kΩ to GND	1	3.8

MIXERS

The ADL5380 has two double-balanced mixers: one for the in-phase channel (I channel) and one for the quadrature channel (Q channel). These mixers are based on the Gilbert cell design of four cross-connected transistors. The output currents from the two mixers are summed together in the resistive loads that then feed into the subsequent emitter follower buffers.

EMITTER FOLLOWER BUFFERS

The output emitter followers drive the differential I and Q signals off chip. The output impedance is set by on-chip 25 Ω series resistors that yield a 50 Ω differential output impedance for each baseband port. The fixed output impedance forms a voltage divider with the load impedance that reduces the effective gain. For example, a 500 Ω differential load has 1 dB lower effective gain than a high (10 kΩ) differential load impedance.

BIAS CIRCUIT

A band gap reference circuit generates the reference currents used by different sections. The bias circuit can be enabled and partially disabled using ENBL (Pin 7). If ENBL is grounded or left open, the part is fully enabled. Pulling ENBL high shuts off certain sections of the bias circuitry, reducing the standing power to about half of its fully enabled consumption and disabling the outputs.

APPLICATIONS INFORMATION

BASIC CONNECTIONS

Figure 77 shows the basic connections schematic for the ADL5380.

POWER SUPPLY

The nominal voltage supply for the ADL5380 is 5 V and is applied to the VCC1, VCC2, and VCC3 pins. Connect ground to the GND1, GND2, GND3, and GND4 pins. Solder the exposed paddle on the underside of the package to a low thermal and

electrical impedance ground plane. If the ground plane spans multiple layers on the circuit board, these layers should be stitched together with nine vias under the exposed paddle. The AN-772 Application Note discusses the thermal and electrical grounding of the LFCSP in detail. Decouple each of the supply pins using two capacitors; recommended capacitor values are 100 pF and 0.1 μ F.

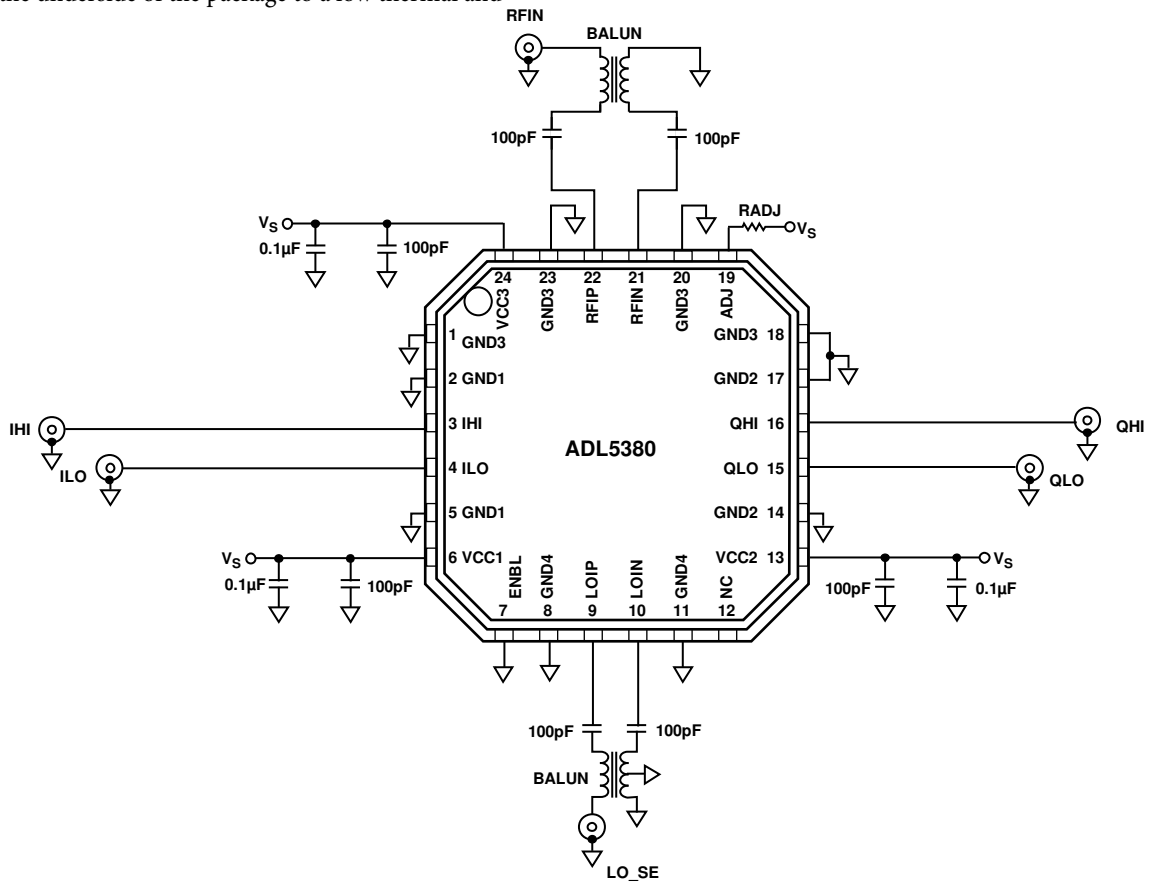


Figure 77. Basic Connections Schematic

07965-078

LOCAL OSCILLATOR AND RF INPUTS

The RF and LO inputs have a differential input impedance of approximately 50 Ω as shown in Figure 78. Figure 79 shows the return loss. For optimum performance, both the LO and RF ports should be ac-coupled and driven differentially through a balun as shown in Figure 80 and Figure 81. The user has many different types of balun to choose from and from a variety of manufacturers. For the data presented in this data sheet all measurements were gathered with the baluns listed below. For applications that are band specific, the recommended baluns are:

- Up to 3 GHz is the Mini-Circuits TC1-1-13.
- From 3 GHz to 4 GHz is the Johanson Technology 3600BL14M050.
- From 4.9 GHz to 6 GHz is the Johanson Technology 5400BL15B050.

For wideband applications covering the entire 400 MHz to 6 GHz range of the ADL5380, the recommended balun is the TCM1-63AX+ from Mini-Circuits. This wide and maximally flat balun allows coverage of the entire frequency range with one component.

The recommended drive level for the LO port is between -6 dBm and +6 dBm.

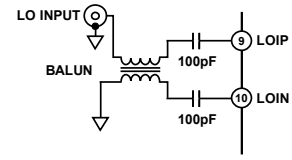


Figure 80. Differential LO Drive

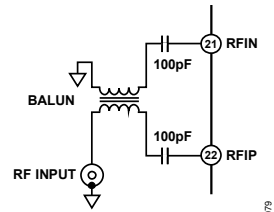


Figure 81. RF Input

Alternatively, if the single-ended drive of both the LO and RF ports is the desired mode of operation, degradations in IIP2 will be observed because of the lack of common mode rejection. The degradation in IIP2 is more prevalent at high frequencies, specifically frequencies greater than 1600 MHz. At low frequencies, the ADL5380 has inherent common mode rejection offering superior IIP2 performance in the 70 dBm range. As shown in Figure 82 and Figure 83, in single-ended mode, the largest performance impact is seen in IIP2 while minimal performance degradation is observed in IIP3.

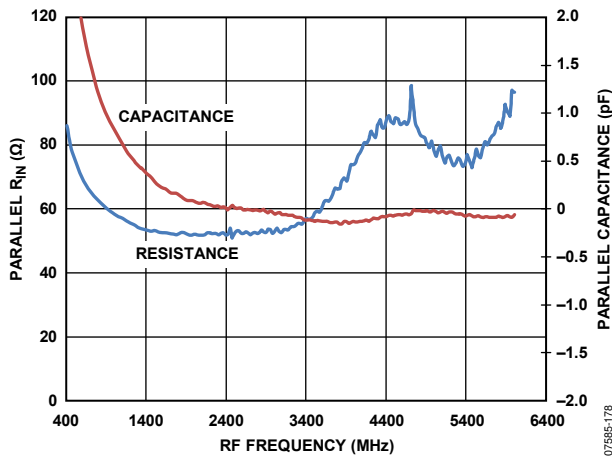


Figure 78. Differential Input Impedance of the RF Port

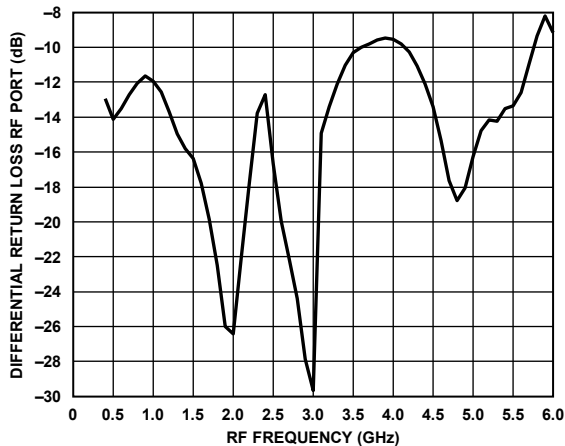


Figure 79. Differential RF Port Return Loss

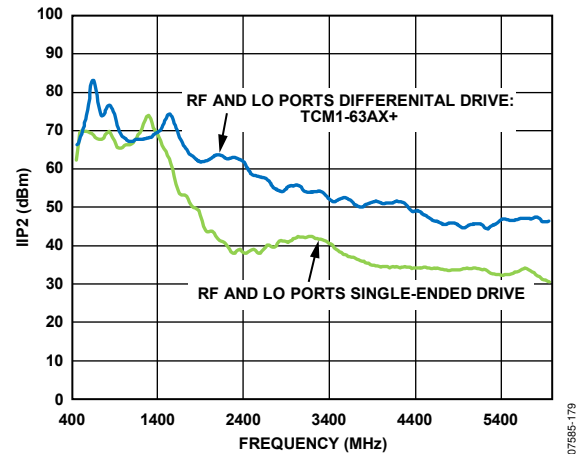


Figure 82. IIP2 vs. Frequency Comparison for Single-Ended and Differential Drive of the RF and LO Ports